

Basic information	
2018/2947(DEA) DEA - Delegated acts procedure Exemption for lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages Supplementing 2008/0240(COD) Subject 3.40.06 Electronics, electrotechnical industries, ICT, robotics 3.70.13 Dangerous substances, toxic and radioactive wastes (storage, transport)	Procedure completed - delegated act enters into force

Key players			
European Parliament	Committee responsible	Rapporteur	Appointed
	<div style="border: 1px solid red; display: inline-block; padding: 2px;">ENVI</div> Environment, Public Health and Food Safety		

Key events			
Date	Event	Reference	Summary
16/11/2018	Non-legislative basic document published	C(2018)07499	
16/11/2018	Initial period for examining delegated act 2 month(s)		
28/11/2018	Committee referral announced in Parliament		
24/01/2019	Delegated act not objected by Parliament		

Technical information	
Procedure reference	2018/2947(DEA)
Procedure type	DEA - Delegated acts procedure
Procedure subtype	Examination of delegated act
Amendments and repeals	Supplementing 2008/0240(COD)
Stage reached in procedure	Procedure completed - delegated act enters into force
Committee dossier	ENVI/8/15029

Documentation gateway			
European Commission			
Document type	Reference	Date	Summary

Non-legislative basic document	C(2018)07499	16/11/2018	
Document attached to the procedure	C(2025)5889	25/08/2025	

Additional information		
Source	Document	Date
European Commission	EUR-Lex	